IPC  ASSOCIATION COI ELECTRONICS INI	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard  Form Typ  http://www.ipc.org/IPC-175x  Distribute				*	* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi					ormation		
upplier In	nformation								,					
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
nsemi											2024-05-16			
Contact Name	e	Title - Contact			1	Phone - Contact*				Email - Contact*				
Product-Env-	-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized R	epresentative*	Title - Representative			1	Phone - Representative*			Email - Representative*					
Product-Env	-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Re	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Date	Version	N	Manufacturing Site		nt*	UOM	Unit Type
		MC74VHC1GT50XV Buffer 5T2G		Buffer			2024-05-16 CN1		N1	2.678		mg	Each	
Ianufactu	uring Proccess Informa	ation												
Ter	Terminal Plating / Grid Array Material Terminal Base Alloy			Alloy J-	J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Te					Temperature	Number of	f Reflow Cycl	es	
Matte Tin (Sn) - annealed		(	CU Alloy 1				<b>260</b> C		С	30	seconds	3		
omments														
vel 1 - maxir	mum time at peak temperat	ure during sol	ldering is 10-3	0 seconds										
or more info	ormation regarding material	l composition	please refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itaability and the Company's remedies for issues that arise regarding information the Supplier provides in this f											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	eneous Material Weight Unit of Measure		Level Substance		CAS	Exempt	Weight	Unit of Measure
Die	0.03	mg	Supplier	Silicon (Si)	7440-21-3		0.03	mg
Lead Frame	1.22	mg	В	Nickel (Ni)	7440-02-0		0.4941	mg
			Supplier	Iron (Fe)	7439-89-6		0.6771	mg
			Supplier	Copper (Cu)	7440-50-8		0.0488	mg
Mold Compound-Black	1.4	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.14	mg
			Supplier	Carbon Black (C)	1333-86-4		0.007	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.203	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0.91	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.14	mg
Plating	0.003	mg	Supplier	Tin (Sn)	7440-31-5		0.003	mg
Wire Bond - Cu	0.025	mg	Supplier	Copper (Cu)	7440-50-8		0.025	mg